



SLOVENSKI STANDARD

SIST EN 4660-004:2011

01-december-2011

**Aeronavtika - Modularne in odprte letalske elektronske arhitekture - 004. del:
Pakiranje**

Aerospace series - Modular and Open Avionics Architectures - Part 004: Packaging

Luft- und Raumfahrt - Modulare und offene Avionikarchitekturen - Teil 004: Paketierung

Série aérospatiale - Architectures Avioniques Modulaires et Ouvertes - Partie 004:
Packaging

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On-board equipment and
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EUROPEAN STANDARD

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Avionikarchitekturen - Teil 004: Packaging

This European Standard was approved by CEN on 26 June 2010.

CEN members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration. Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CEN member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CEN member into its own language and notified to the CEN-CENELEC Management Centre has the same status as the official versions.

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COMITÉ EUROPÉEN DE NORMALISATION
EUROPÄISCHES KOMITEE FÜR NORMUNG**Management Centre: Avenue Marnix 17, B-1000 Brussels**

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EN 4660-004:2011 (E)**Foreword**

This document (EN 4660-004:2011) has been prepared by the Aerospace and Defence Industries Association of Europe - Standardization (ASD-STAN).

After enquiries and votes carried out in accordance with the rules of this Association, this Standard has received the approval of the National Associations and the Official Services of the member countries of ASD, prior to its presentation to CEN.

This European Standard shall be given the status of a national standard, either by publication of an identical text or by endorsement, at the latest by August 2011, and conflicting national standards shall be withdrawn at the latest by August 2011.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN [and/or CENELEC] shall not be held responsible for identifying any or all such patent rights.

According to the CEN/CENELEC Internal Regulations, the national standards organizations of the following countries are bound to implement this European Standard: Austria, Belgium, Bulgaria, Croatia, Cyprus, Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

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0 Introduction

0.1 Purpose

This document is produced under contract ASAAC Phase II Contract n°97/86.028.

The purpose of the ASAAC Programme is to define and validate a set of open architecture standards, concepts and guidelines for Advanced Avionics Architectures (A3) in order to meet the three main ASAAC drivers. The standards, concepts and guidelines produced by the Programme are to be applicable to both new aircraft and update programmes from 2005.

The three main goals for the ASAAC Programme are:

1. Reduced life cycle costs.
2. Improved mission performance.
3. Improved operational performance.

The ASAAC standards are organised as a set of documents including:

A set of agreed standards that describe, using a top down approach, the Architecture overview to all interfaces required to implement the core within avionics system.

The guidelines for system implementation through application of the standards.

The document hierarchy is given hereafter (in this figure the document is highlighted)

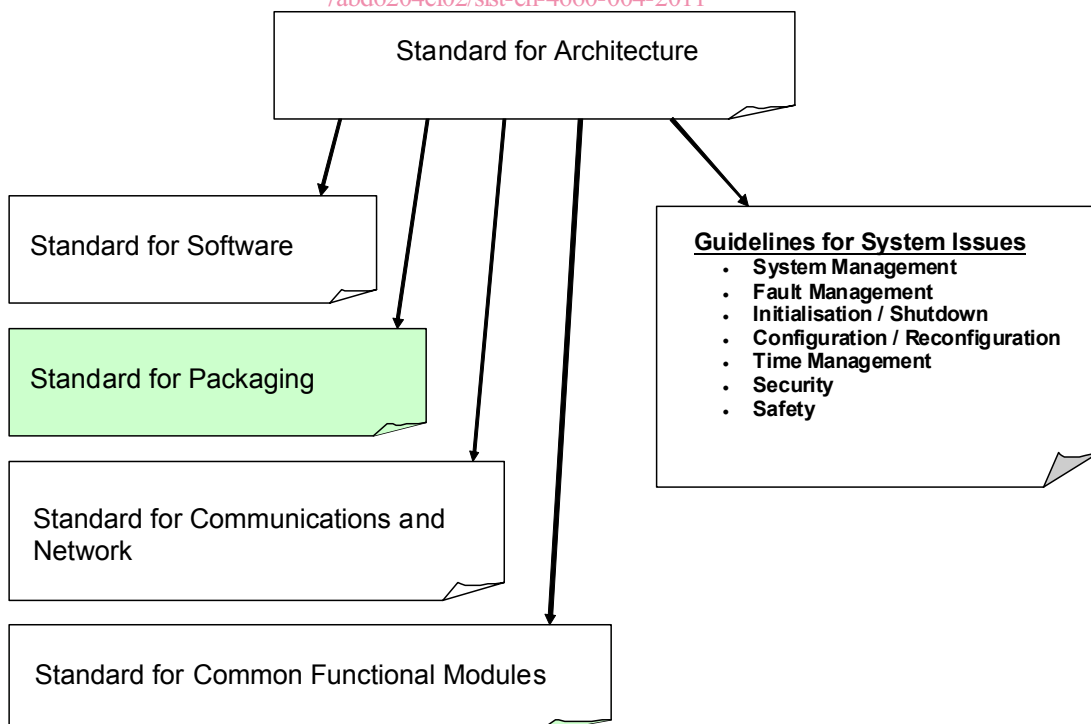


Figure 1 — ASAAC Standard Documentation Hierarchy

EN 4660-004:2011 (E)**0.2 Document structure**

The document contains the following clauses:

Clause 1, Scope.

Clause 2, Normative references.

Clause 3, Terms, definitions and abbreviation.

Clause 4, Generic module specification.

Clause 5, Module Mechanical Tests.

Clause 6, Guidelines for a rack slot.

Clause 7, Typical modular avionics environment.

1 Scope

The purpose of this standard is to establish uniform requirements for Packaging for the Common Functional Modules (CFM) within an Integrated Modular Avionic (IMA) system, as defined per ASAAC. It comprises the module physical properties and the Module Physical Interface (MPI) definitions together with guidelines for IMA rack and the operational environment.

The characteristics addressed by the Packaging Standard are:

Interchangeability:

- For a given cooling method all modules conforming to the packaging standard will function correctly when inserted into any rack slot conforming to the standard for the cooling method.
- All modules conforming to the Module Physical Interface (MPI) definitions for connector, IED and cooling interface will function correctly when inserted into any rack slot conforming to the same MPI definition.

Maintainability:

- All modules are easily removable at first line.
- No special tools required at first line.
- No manual adjustment is necessary when installing modules. No tool is required for installation or removal of the modules.
- Mechanical keying is provided that prevents insertion of a module into a rack slot that may cause an unsafe condition.

The Module Physical Interface definition, contained within this standard, does not include the properties of the signalling used in the optical interface (e.g. wavelength). These are covered in EN 4660-003.

2 Normative references

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

EN 2101, *Aerospace series — Chromic acid anodizing of aluminium and wrought aluminium alloys*

EN 2284, *Aerospace series — Sulphuric acid anodizing of aluminium and wrought aluminium alloys*

EN 2437, *Aerospace series — Chromate conversion coatings (yellow) for aluminium and aluminium alloys*

EN 4660-001, *Aerospace series — Modular and Open Avionics Architectures — Part 001: Architecture*

EN 4660-002, *Aerospace series — Modular and Open Avionics Architectures — Part 002: Common Functional Modules*

EN 4660-003, *Aerospace series — Modular and Open Avionics Architectures — Part 003: Communications/Network*

EN 4660-005, *Aerospace series — Modular and Open Avionics Architectures — Part 005: Software*

ASAAC2-GUI-32450-001-CPG Issue 01, *Final Draft of Guidelines for System Issues* ¹⁾

— Volume 1 — System Management.

— Volume 2 — Fault Management.

— Volume 3 — Initialisation and Shutdown.

— Volume 4 — Configuration / Reconfiguration.

— Volume 5 — Time Management.

— Volume 6 — Security.

— Volume 7 — Safety.

ARINC 600, *Air transport avionics — Equipment interfaces.*

Def Stan 03-18, *Chromate Conversion Coatings (Chromate Filming Treatments) Grades: Standard and Brushing for Aluminium and Aluminium Alloys.*

Def Stan 03-24, *Chromic Acid Anodizing of Aluminium and Aluminium Alloys.*

Def Stan 03-25, *Sulphuric Acid Anodizing of Aluminium and Aluminium Alloys.*

1) In preparation at the date of publication of this standard.

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BS 5599, *Specification for hard anodic oxidation coatings on aluminium and its alloys for engineering purposes.*
2)

MIL-C-26074E, *Coatings, Electroless Nickel Requirements.*

MIL-A-8625E, *Anodic Coatings for Aluminium and Aluminium Alloys.*

MIL-C-81706, *Chemical Conversion Materials for Coating Aluminium and Aluminium Alloys.*

MIL-C-5541, *Chemical Conversion Coatings on Aluminium and Aluminium Alloys.*

3 Terms, definitions and abbreviations**3.1 Terms and definitions**

Use of “shall”, “should” and “may” within the standards observe the following rules:

- The word SHALL in the text express a mandatory requirement of the standard.
- The word SHOULD in the text expresses a recommendation or advice on implementing such a requirement of the standard. It is expected that such recommendations or advice will be followed unless good reasons are stated for not doing so.
- The word MAY in the text expresses a permissible practice or action. It does not express a requirement of the standard.

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3.2 Abbreviations

AFA	Air Flow Around	SIST EN 4660-004:2011
AFT	Air Flow Through	
ARINC	Aeronautical Radio Inc	
ASAAC	Allied Standard Avionics Architecture Council	
CC	Conduction Cooled	
CFM	Common Functional Module	
DAF	Direct Air Flow	
EMC	ElectroMagnetic Compatibility	
IED	Insertion Extraction Device	
IMA	Integrated Modular Avionics	
MBU	Multiple Bit Upset	

2) Replaces Def Stan 03-26.

MPI	Module Physical Interface
MT	Mechanical Transfer
NBC	Nuclear, Biological and Chemical
PSD	Power Spectral Density
SEU	Single Event Upset

3.3 Precedence

Figures in this document have precedence over text.

3.4 Definition of terms

3.4.1 General terms

Backplane	A structure containing optical and electrical communication paths and electrical power supply wiring between modules. This shall be a removable structure or integrated into the rack.
Cassette	Mechanical frame enclosing the electrical components of the module.
Connector	A device to provide all of the electrical and optical connections between the cassette and the backplane. The connector fixed to the module cassette plugs into the corresponding connector of the backplane. It comprises a shell, inserts contacts and ferrules.
Contact	A single signal connection, either an electrical pin/socket or a single fibre. In the case of fibre optic contacts this does not necessarily imply the mating parts are in mechanical contact.
Cooling Interface	Surface which contributes to the removal of heat from the module.
Ferrule	A housing and alignment device for one or more optical fibres.
Insert	A section of a connector containing a number of ferrules or contacts.
Insertion Extraction Device (IED)	A device to aid the insertion and extraction of the module from the rack and give mechanical advantage over the mating forces associated with the connector. It also provides the retention system for the module within the rack such that the module connector remains mated under all conditions specified.
Module	The module is a grouping of electronic devices, assembled together to perform a specific function, into a flight-line protected hardware assembly. This is the Common Functional Module. The CFM is replaceable at first line.
Rack	A mechanical arrangement for housing avionics equipment. This provides physical support, environmental protection and cooling for the modules.
Shell	The outer mating parts of the connector that provide the structure of the connector, fixings to the module and backplane parts and the support for the Inserts.

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3.4.2 Module mechanical items

A Common Functional Module comprises:

- A cassette.
- A connector.
- An insertion extraction device.

The volume of the cassette is delimited by a cuboid. The module is referenced against a Cartesian Reference System as represented on Figure 2.

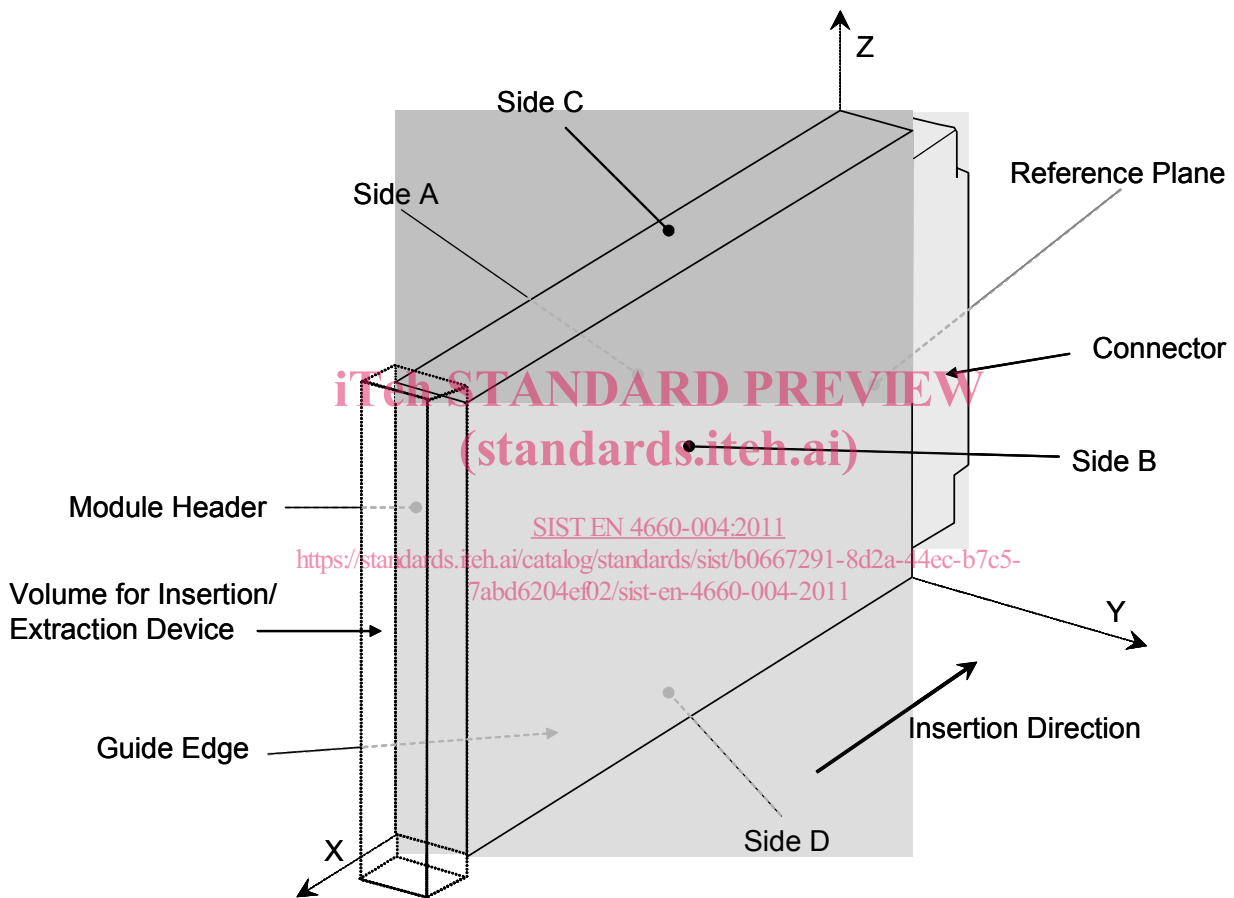


Figure 2 — Module definitions

Guide Edge	Edge of the CFM running along the X axis. It defines the location of the module within the rack.
Height	The cassette dimension in the Z-axis. It is measured from cassette Side C to cassette Side D.
Length	The cassette dimension in the X-axis measured from the Reference Plane to the module header (this excludes the Insertion Extraction Device and the connector).
Module header	The surface of the cassette parallel to the Reference Plane, and opposite to the cassette surface contained within the Reference Plane The IED shall be mounted on this surface.
Side A	Surface of the cassette contained within the X, Z plane. Viewing the module in the direction of insertion, with the cassette Side C at the top, Side A is to the left.
Side B	Surface of the cassette parallel to and furthest from the X, Z plane. Viewing the module in the direction of insertion, with the cassette Side C at the top, Side B is to the right.
Side C	Surface of the cassette parallel to and furthest from the X, Y plane. It contains one of the two cassette cooling interfaces, the other being within Side D.
Side D	Surface of the cassette contained within the X, Y plane. It contains one of the two cassette cooling interfaces, the other being within Side C.
Reference Plane	Plane defined by the Y and Z axis. It is perpendicular to the direction of insertion of the module and passes through the mating surface between the cassette and the connector.
Width	The cassette dimension in the Y-axis of the module, measured from Side A to Side B.

3.4.3 Tolerances

Unless otherwise stated, tolerances shall be $\pm 0,2$ mm.

4 Generic module specification

4.1 Introduction

This clause specifies the physical properties and the principle physical interfaces for ASAAC Common Functional Modules, i.e. the Module Physical Interface (MPI). The MPI comprises:

- The Connector Interface between Common Functional Module and Backplane.
- The Cooling Interface.
- The Insertion Extraction Device (IED).